Product Change Notification: DSNO-23ZLEM284

Date:

12-Dec-2025

Product Category:

Photoelectric/Ionization Smoke Detector

Notification Subject:

CCB 7734 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as new bond wire material for RE370V28, RE370V28T, RE46C400V28, RE46C400V28T, RE46C401V28, RE46C401V28T, RE46C420V28T, RE46C421V28T, RE46C422V32, RE46C422V32T, RE46C700IV28, RE46C700IV28T, RE46C701IV28, RE46C701IV28T, RE46C705IV32, RE46C705IV32T, RE46C707IV32, RE46C707IV32T, RE46C730IV28 and RE46C730IV28T catalog part numbers (CPN) available in 28L VQFN (4x4x1.0mm) and 32L VQFN (5x5x1mm) packages at MTAI assembly site.

Affected CPNs:

DSNO-23ZLEM284_Affected_CPN_12122025.pdf
DSNO-23ZLEM284_Affected_CPN_12122025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as new bond wire material for RE370V28, RE370V28T, RE46C400V28, RE46C400V28T, RE46C401V28, RE46C401V28T, RE46C420V28T, RE46C421V28T, RE46C422V32, RE46C422V32T, RE46C700IV28, RE46C700IV28T, RE46C701IV28, RE46C701IV28T, RE46C705IV32, RE46C705IV32T, RE46C707IV32, RE46C707IV32T, RE46C730IV28 and RE46C730IV28T catalog part numbers (CPN) available in 28L VQFN (4x4x1.0mm) and 32L VQFN (5x5x1mm) packages at MTAI assembly site.

Pre and Post Summary Changes:

<table>
<tr><th></th><th colspan="2">Pre Change</th><th colspan="2">Post Change</th><th>Change (Yes/No)</th></tr>
<tr><td>Assembly Site</td><td colspan="2">Microchip Technology Thailand (HQ) (MTAI)</td><td colspan="2">Microchip Technology Thailand (HQ) (MTAI)</td><td>No</td></tr>
<tr><td>Wire Material</td><td colspan="2">Au</td><td colspan="2">CuPdAu</td><td>Yes</td></tr>
<tr><td>Die Attach Material</td><td colspan="2">3280</td><td colspan="2">*QMI519</td><td>Yes</td></tr>
<tr><td>Molding Compound Material</td><td colspan="2">G700LTD</td><td colspan="2">G700LTD</td><td>No</td></tr>
<tr><td>Lead-Frame Material</td><td colspan="2">C194</td><td colspan="2">C194</td><td>No</td></tr>
<tr><td>DAP Surface Prep</td><td>Ag</td><td>Bare Cu</td><td>Ag</td><td>Bare Cu</td><td>No</td></tr>
</table>

Note 1: *PFAS-free material.

Note 2: *The qualification of the new PFAS-free die attach material, QMI519, was officially released via PCN #CENO-16EGCZ399.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire as a new wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 04 February 2026 (date code: 2606)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	July 2025					>	**December 2025**				>	**February 2026**			
Work Week	27	28	29	30	31		49	50	51	52		06	07	08	09
Initial PCN Issue Date					X										
Qual Report Availability								X							

Final PCN Issue Date								X							
Estimated Implementation Date												X			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: July 29, 2025: Issued initial notification. The new die attach material was qualified via PCN #**CENO-16EGCZ399** on July 22, 2025.
December 12, 2025: Issued final notification. Attached the Qualification Report. Revised the affected parts list to add RE46C707IV32 and RE46C707IV32T catalog part numbers (CPN). Added a 'Change (Yes/No)' column to the Pre and Post Change Summary table. Provided estimated first ship date to be on February 04, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-23ZLEM284_Qual Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.